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(74) Agent: OHIE, Kunihisa; OHIE Patent Office,
Selva-Mingyocho 6F, 14-6, Nihonbashi-Ningyocho
2-chome, Chuo-ku, Tokyo 103-0013 (JP).

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(71) Applicant: SHOWA DENKO K.K. [JP/JP]; 13-9, Shiba Daimon 1-chome, Minato-ku, Tokyo 105-8518 (JP).

(72) Inventors: NAGAO, Yuji; c/o Showa Denko K.K., 13-9, Shiba Daimon 1-chome, Minato-ku, Tokyo 105-8518 (JP).
YAMAMOTO, Ryuji; c/o Showa Denko K.K., 13-9, Shiba Daimon 1-chome, Minato-ku, Tokyo 105-8518 (JP).

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(54) Title: SEMICONDUCTIVE RESIN COMPOSITION

(57) Abstract: The invention relates to a semiconductive resin composition containing at least two kinds of conductive fillers, wherein the difference in threshold values of percolation between at least two kinds of the conductive fillers is within a range of 10 to 50 mass%. The semiconductive resin composition of the present invention can be used widely in various form of molded products, such as component used for transport in a clean room, spin chuck, IC test socket, various rollers installed in copier, seamless belt, bearing, antistatic fiber, member for electrostatic coating, fuel tube, part around fuel or chemical tube.

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